

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBRB Series 0.5mm Board to Board Connector	SPEC.NO.: SPCB012E
REVISIONS	ECNT120076		PAGE: 1/5

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES No. : CBRB Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C. BOARD

6.1 Thickness: 0.8 mm (.031") ~ 1.6 mm (.063")
6.2 P.C. Board Layout: See attached drawings

REVIEWED : Eisley APPROVED : Eisley VERIFIED : Michelle .

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBRB Series 0.5mm Board to Board Connector	SPEC.NO.: SPCB012E
REVISIONS	ECNT120076		PAGE: 2/5

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		0.5A 50V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 10 mA max.	Less than 50 mΩ
7.3	Dielectric strength	When applied AC 500V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 500 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact retaining force in insulator	Retention speed 25± 3 mm per minute form housing	More than 100 gram
8.2	Durability	Connector shall be subjected to 30 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial
8.3	Mating force	Speed 25± 3 mm per minute	0.07 x no.of Contacts kgf max.
8.4	Unmating force	Speed 25± 3 mm per minute	0.02 x no.of Contacts kgf min.

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.2	Solder ability	Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area
9.3	Resistance to soldering heat	Lead-Free Process: Soldering time: 20 second Max. Soldering pot: 250~260°C Refer Reflow temperature profile(11.1)	No damage

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBRB Series 0.5mm Board to Board Connector	SPEC.NO.: SPCB012E
REVISIONS	ECNT120076		PAGE: 3/5

	ITEM	TEST CONDITION	REQUIREMENT
9.4	Heat aging	105± 2°C, 96 hours	No damage
9.5	Humidity	60±2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.6	Temperature cycling	One cycle consists of : (1) -55 ⁺⁰ ₋₃ °C , 30 min. (2)Room temp. 10-15 min. (3) 105 ⁺³ _{.0} °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.7	Salt spray	Temperature: 35 ± 3°C Solution: 5 ± 1% Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage Contact resistance: Less than twice of initial

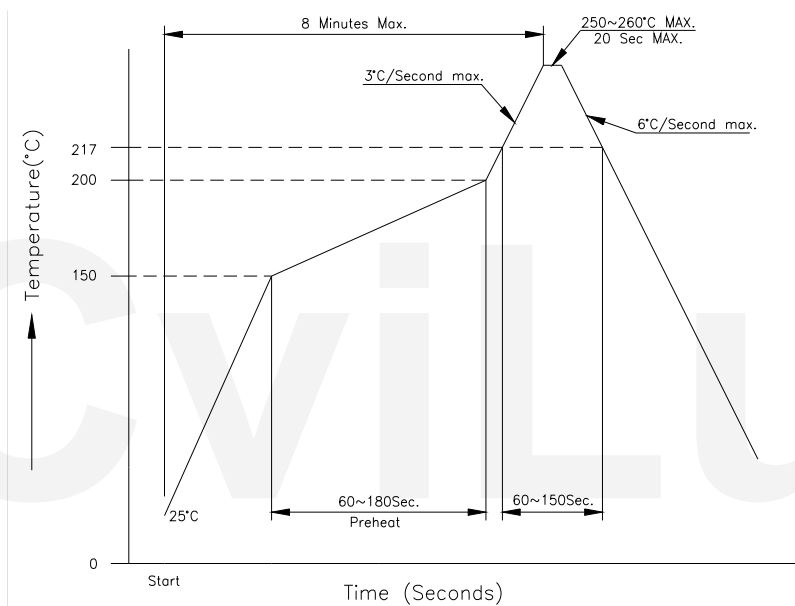
ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBRB Series 0.5mm Board to Board Connector	SPEC.NO.: SPCB012E
REVISIONS	ECNT120076		PAGE: 4/5

10. AMBIENT TEMPERATURE RANGE:

-40 ~ +105°C ; + 215°C intermittent (Vapor Phase Solder Reflow) for SMT type

11. Recommended IR Reflow Temperature Profile:

11.1 Using Lead-Free Solder Paste

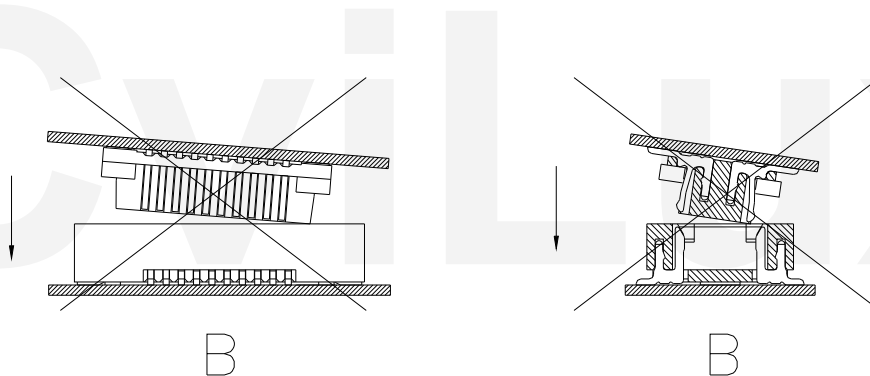
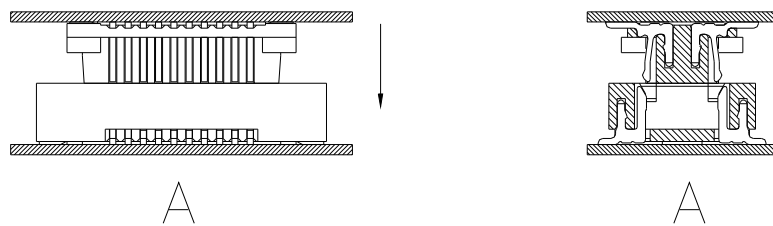


ENGINEERING DEPT.		PRODUCT SPECIFICATION For CBRB Series 0.5mm Board to Board Connector	SPEC.NO.: SPCB012E
REVISIONS	ECNT120076		PAGE: 5/5

12. INSTRUCTION UPON USAGE

12.1 At Mating:

Please do not insert diagonally in following figure B when the connector mating starts.
Please insert as in parallel as possible to the utmost to mating with connector as shown in following figure A .Please insert until the connector bumps.



12.2 At Extraction:

As regard extraction is as in parallel as possible to straight at mating axis to the utmost to the mating With connector.

Or. please swing right to left slightly.(Refer to following figure C)

Please do not excess twist extraction. .(Refer to following figure D)

